



Features:

- High temperature masking tape and dots are ideal for masking gold fingers of printed circuit boards during wave solder or solder dip process, as well as for solder wave masking and electrical insulation.
- This high temperature tape is a polyimide, pressure sensitive, adhesive tape with silicon resin, which shows excellent dielectric insulation properties, high heat resistance and excellent solvent resistance. These properties result in a tape with remarkable dimensional stability and excellent electrical and physical properties over a wide range of temperatures.
- High temperature masking dots are composed of a polyimide film masking dots with silicone adhesive on a clear easy release liner. High temperature masking dots are both flame and chemical resistant.
- This product is neither corrosive nor ozone depleting and is both flame and chemical resistant.



Technical Properties:	DIN Value:	ASTM Value:
Structure	Silicon Adhesive/Polyimide Film	
Base Film Thickness	0.025mm	1.0MIL
Total Thickness	0.070mm	2.8MIL
Peel Strength	2.7N/cm	25Oz/In
Tensile Strength	40N/cm	22lbs/In
Elongation	50%	50%
Heat Resistance (Short Term)	290°C	554°F
Heat Resistance	230°C	446°C
Appearance	Amber	Amber

Product Code:	Description:	Dimensions (mm):	Additional Notes:
1503254	High Temperature Masking Dots	6	Per Roll of 1000 (Ref: 053-1000)

Important Notice: This data sheet and its contents (the "Information") belong to the members of the Premier Farnell group of companies (the "Group") or are licensed to it. No licence is granted for the use of it other than for information purposes in connection with the products to which it relates. No licence of any intellectual property rights is granted. The Information is subject to change without notice and replaces all data sheets previously supplied. The Information supplied is believed to be accurate but the Group assumes no responsibility for its accuracy or completeness, any error in or omission from it or for any use made of it. Users of this data sheet should check for themselves the Information and the suitability of the products for their purpose and not make any assumptions based on information included or omitted. Liability for loss or damage resulting from any reliance on the Information or use of it (including liability resulting from negligence or where the Group was aware of the possibility of such loss or damage arising) is excluded. This will not operate to limit or restrict the Group's liability for death or personal injury resulting from its negligence. Multicomp is the registered trademark of the Group. © Premier Farnell plc 2011.